

TG-4040P

Preliminary Data Sheet



Description

TG-4040P is an ultra conformable, high performance putty type gap filler. It is designed for when heat transfer is needed between delicate components where the pressure must be minimised. TG-4040P is designed to fill gaps from 0.25 – 8mm with little or no stress generated. The silicone based formulation will adhere to all surfaces, such as metal housings, ceramic and plastic IC packages and FR4 boards to give a low thermal resistance path for heat transfer.

TG-4040P is available in 30cc syringes, 6 and 12oz cartridges and 5 gallon pails

Property	TG-4040P	Test Method
Colour	Dark blue	-
Description	One part silicone based putty	-
Viscosity /mPas	3,000,000	-
Density / gcm ³	2.6	ASTM D792
Thermal Conductivity / W/mk	3	ASTM D5470
D4-10 /ppm	50	GC / MS
TML / %	0.3%	ASTM E595
CVCM / %	0.09	ASTM E595
Volume Resistivity / Ohm cm ¹	10 ¹⁴	
Working Temperature / °C	-50 to 180°	